

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20200203001 Datasheet for MSP430FR2522, MSP430FR2512 MSP430FR2422, MSP430FR2476, MSP430FR2475 Information Only

Date: February 18, 2020 **To:** PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN ww admin_team@list.ti.com).

Sincerely,

PCN Team SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
MSP430FR2422IPW16	null
MSP430FR2422IRHLT	null
MSP430FR2512IPW16	null
MSP430FR2512IRHLT	null
MSP430FR2522IPW16	null
MSP430FR2522IRHLT	null

Technical details of this Product Change follow on the next page(s).

PCI	Nu	mber:		002030					18, 2020
Titl	e:	Datasheet fo MSP430FR24		430FR	252	22, MSP430FR25	12, MSP43	0FR	R2422, MSP430FR2476,
Cuc	tom	er Contact:		Manag	or			Do	ept: Quality Services
			<u>I CIV</u>	Mariag	<u>CI</u>			DC	Quality Services
Clia		Type:				Danima			W-f D Cit-
		embly Site				Design		H	Wafer Bump Site
屵		embly Process			\boxtimes	Data Silect		Н	Wafer Bump Material
\sqcup		embly Material			빝	Part number ch	ange	Щ	Wafer Bump Process
		hanical Specifi			<u> </u>	Test Site		Щ	Wafer Fab Site
	Pack	king/Shipping/	<u>Labeli</u>	ng		Test Process		Щ	Wafer Fab Materials
									Wafer Fab Process
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						further details.			
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•	INS	STRUMENTS					SLASE		-JANUARY 2018-REVISED DECEMBER 2019
Char	naes f	rom August 20, 2	019 to I	Decemb	er 1	0. 2019	OLAGI		Page
	.9	· · · · · · · · · · · · · · · · · · ·				, _,			9-
•	Cha	anged the note that	t begins	"Supply	volt	age changes faster th	nan 0.2 V/µs o	an tri	igger a BOR reset" in
	Sec	tion 5.3, Recomm	ended C	perating	Co	nditions			
	Add	led the note that b	egins "T	l recomr	nen	ds that power to the D	OVCC pin mus	t not	exceed the limits" in
	Sec	tion 5.3, Recomm	ended C	perating	Co	nditions			
•	Cha	anged the note that	t begins	"A capa	cito	tolerance of ±20% o	r better is requ	uired.	" in Section 5.3,
	Red	commended Opera	ting Co	nditions .					
•	Add	led the note "See I	MSP430	32-kHz	Cry	stal Oscillators for de	tails on crysta	sect	tion, layout, and testing" to
	Tab	le 5-4, XT1 Crysta	I Oscilla	ator (Low	Fre	quency)			24
•	Cha	anged the note that	t begins	"Require	es e	xternal capacitors at I	ooth terminals	" in	Table 5-4, XT1 Crystal
	Osc	illator (Low Freque	ency)						24
•	Add	led the t _{TA,cap} para	meter in	Table 5	-13,	Timer_A			30
•									ply and Input Range Conditions. 37
•	Add	led the note that b	egins "t	Sample = Ir	1(2 ⁿ⁺	¹) × τ" in Table 5-2	1, ADC, 10-B	it Tim	ning Parameters 37
•									ice Descriptors 60
•	Add	led "1.5-V reference	e factor	" in Tabl	e 6-	18, Device Descriptor	ຮ		<u>61</u>
-i-	Tov	40							
70	TEX	AS TRUMENTS							MSP430FR2422
_	1145	TRUMENTS					SLASE	E5C -	-JANUARY 2018-REVISED DECEMBER 2019
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Char	iges fi	rom August 20, 2	019 to [Decembe	er 10	0, 2019			Page
	Cha	nand the note that	hagina	"Cumphy	vale	aga ahangaa faatar ti	on 0.2 \///up a	an tri	igger a BOD recet " in
•									igger a BOR reset" in
									<u>13</u>
•	Add	ed the note that be	egins 1	recomr	nen	ds that power to the L	OVCC pin mus	st not	exceed the limits" in
	Sec	tion 5.3, Recomme	ended C	perating	Co	nditions			<u>13</u>
•	Cha	inged the note that	begins	"A capa	citor	tolerance of ±20% o	r better is requ	uired.	" in Section 5.3,
	Rec	ommended Opera	ting Co	nditions .					<u>13</u>
•	Add	ed the note "See /	MSP430	32-kHz	Cry	stal Oscillators for de	tails on crysta	sect	tion, layout, and testing" to
	Tab	le 5-4, XT1 Crysta	l Oscilla	tor (Low	Fre	quency)			
	Cha	inged the note that	begins	"Require	es e	xternal capacitors at I	both terminals	" in	Table 5-4, XT1 Crystal
	Osc	illator (Low Freque	ency)						20
•	Add	ed the t _{TA,cap} parar	meter in	Table 5	-13,	Timer_A			ply and Input Range Conditions. 33 ning Parameters. 33 ice Descriptors 55
•	Con	rected the test con	ditions	for the R	par	ameter in Table 5-20	, ADC, Power	Sup	ply and Input Range Conditions. 33
	Add	ed the note that be	egins "ta	Sample = Ir	1(2n+	1) × τ" in Table 5-2	1, ADC, 10-B	it Tim	ning Parameters 33
	Cha	nged the CRC cov	vered er	nd addre	ss to	0x1AF5 in note (1) i	n Table 6-18.	Devid	ice Descriptors 55
	Add	ed "1.5-V reference	e factor	" in Tabl	e 6-	18. Device Descriptor	· · · · · · · · · · · · · · · · · · ·		56
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MSP430FR2476, MSP430FR2475





Changes from April 26, 2019 to December 10, 2019

Page

•	Changed the note that begins "Supply voltage changes faster than 0.2 V/µs can trigger a BOR reset" in Section 5.3, Recommended Operating Conditions	21
	Added the note that begins "TI recommends that power to the DVCC pin must not exceed the limits" in	
	Section 5.3, Recommended Operating Conditions	21
•	Changed the note that begins "A capacitor tolerance of ±20% or better is required" in Section 5.3,	
	Recommended Operating Conditions	21
•	Added the note "See MSP430 32-kHz Crystal Oscillators for details on crystal section, layout, and testing" to	
	Table 5-4, XT1 Crystal Oscillator (Low Frequency)	28
•	Changed the note that begins "Requires external capacitors at both terminals" in Table 5-4, XT1 Crystal	1
	Oscillator (Low Frequency)	28
•	Added the t _{TA,cap} parameter in Table 5-13, Timer_A.	35
•	Added the t _{TB,cap} parameter in Table 5-14, <i>Timer_B</i> .	35
•	Corrected the test conditions for the R _I parameter in Table 5-21, ADC, Power Supply and Input Range Conditions.	42
•	Added the note that begins " $t_{Sample} = ln(2^{n+1}) \times \tau$ " in Table 5-22, ADC, Timing Parameters	42
•	Changed CRC covered end address to 0x1AF7 in table note (1) in Table 6-30 , Device Descriptors	72

The datasheet number will be changing.

Device Family	Change From:	Change To:
MSP430FR2522, MSP430FR2512	SLASEE4B	SLASEE4C
MSP430FR2422	SLASEE5B	SLASEE5C
MSP430FR2476, MSP430FR2475	SLASE07A	SLASE07B

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/MSP430FR2522

http://www.ti.com/product/MSP430FR2422

http://www.ti.com/product/MSP430FR2475

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

MSP430FR2512IPW16	MSP430FR2512IPW16R	MSP430FR2512IRHLR	MSP430FR2512IRHLT
MSP430FR2522IPW16	MSP430FR2522IPW16R	MSP430FR2522IRHLR	MSP430FR2522IRHLT
MSP430FR2422IPW16	MSP430FR2422IPW16R	MSP430FR2422IRHLR	MSP430FR2422IRHLT
MSP430FR2475TPT	MSP430FR2475TPTR	MSP430FR2475TRHAR	MSP430FR2475TRHAT
MSP430FR2475TRHBR	MSP430FR2475TRHBT	MSP430FR2476TPT	MSP430FR2476TPTR
MSP430FR2476TRHAR	MSP430FR2476TRHAT	MSP430FR2476TRHBR	MSP430FR2476TRHBT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

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